12 January 2004 Updated Search

L Number Hits DB Search Text Time stamp 6214193.pn. 6099702.pn. USPAT; 2003/04/25 US-PGPUB; 11:32 EPO; JPO; **DERWENT** 3950184.pn. USPAT; 2003/04/25 US-PGPUB; 11:58 EPO; JPO; DERWENT 14 3950184.URPN. USPAT 2003/04/25 11:58 ("3141793" | "3656173" | "3950184" | "4451507" | 5 USPAT 2003/04/25 "5084483").PN. 12:01 ("3798056" | "3950184" | "4339319" | "4373988" | 17 USPAT 2003/04/25 "4466864" | "4856456" | "5000827" | "5169408" | 13:58 "5312487" | "5340437" | "5472592" | "5670034" | "5677000" | "5893966" | "5930549" | "6077412" | "6099702").PN. 5000827.URPN. USPAT 33 2003/04/25 12:04 53 5169408.URPN. USPAT 2003/04/25 12:41 5000827.URPN. 33 USPAT 2003/04/25 12:50 2247 204/212,225,237,275.1.ccls. USPAT; 2003/04/25 US-PGPUB; 13:58 EPO; JPO; DERWENT 773 204/224r.ccls. USPAT; 2003/04/25 US-PGPUB: 13:58 EPO: JPO: DERWENT 2837 204/212,225,237,275.1.ccls. 204/224r.ccls. USPAT: 2003/04/25 US-PGPUB; 14:00 EPO; JPO; **DERWENT** 2190 118/416,500,501.ccls. 2003/04/25 USPAT; US-PGPUB; 14:01 EPO; JPO; DERWENT 5015 (204/212,225,237,275.1.ccls. 204/224r.ccls.) USPAT: 2003/04/25 118/416,500,501.ccls. US-PGPUB; 14:01 EPO; JPO; **DERWENT** 1027 ((204/212,225,237,275.1.ccls. 204/224r.ccls.) 2003/04/25 USPAT; 118/416,500,501.ccls.) and (semiconductor or wafer) US-PGPUB; 14:02 EPO; JPO; **DERWENT** 557 (((204/212,225,237,275.1.ccls. 204/224r.ccls.) 2003/04/25 USPAT; 118/416,500,501.ccls.) and (semiconductor or wafer)) US-PGPUB; 14:02 and (spinning or spin or spun or rotate or rotated or EPO; JPO; rotating) DERWENT

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-	90	((((204/212,225,237,275.1.ccls. 204/224r.ccls.) 118/416,500,501.ccls.) and (semiconductor or wafer)) and (spinning or spin or spun or rotate or rotated or	USPAT; US-PGPUB; EPO; JPO;	2003/04/25 14:36
		rotating)) and (recycle or recycling or recylcer or reclaim or reclamation or recycled or reclaimed or	DERWENT	
-	3	recover or recovered or recovery or recovering) ("5922138" "6168691" "6187152").PN.	USPAT	2003/04/25 14:29
-	0	6352623.URPN.	USPAT	2003/04/25
-	3776	205/122,123,157,220.ccls. 427/98,299,352.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:34
-	940	(205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:34
-	504	((205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)) and (cleaning or clean or cleaned or rinsed or rinse or rinsing or wash or washing or washed)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:35
-	53	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)) and (cleaning or clean or cleaned or rinsed or rinse or rinsing or wash or washing or washed)) and (recycle or recycling or recylcer or reclaim or reclamation or recycled or reclaimed or recover or recovered or recovery or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:36
-	90	recovering) ((((204/212,225,237,275.1.ccls. 204/224r.ccls.) 118/416,500,501.ccls.) and (semiconductor or wafer)) and (spinning or spin or spun or rotate or rotated or rotating)) and (recycle or recycling or recycler or reclaim or reclamation or recycled or reclaimed or recover or recovered or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 15:01
-	53	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)) and (cleaning or clean or cleaned or rinsed or rinse or rinsing or wash or washing or washed)) and (recycle or recycling or recycler or reclaim or reclamation or recycled or reclaimed or recover or recovered or recovery or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:37
-	225	recovering) (((205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)) and (cleaning or clean or cleaned or rinsed or rinse or rinsing or wash or washing or washed)) and (spin or spinning or spun or rotate or rotating or rotated or revolve or revolved or revolving)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:37

	40	((((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
-	40	and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:37
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	14.37
		washing or washed)) and (spin or spinning or spun or	DERWENT	
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		revolving)) and (recycle or recycling or recycler or		
		reclaim or reclamation or recycled or reclaimed or		
		recover or recovered or recovery or recovering)	110047	2002/0//40
-	11	(U5-6099702-\$ or U5-6214193-\$ or U5-5677000-\$	USPAT;	2003/06/10
		or US-3950184-\$ or US-6551487-\$ or	US-PGPUB;	11:50
		US-6299751-\$).did.	EPO; JPO;	
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-	1	2000wo-us28210.ap,prai.	USPAT;	2003/06/10
			US-PGPUB;	11:53
			EPO; JPO;	
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-	16	6099702.URPN.	USPAT	2003/06/10 11:51
_	15	("3798056" "3950184" "4339319" "4373988"	USPAT	2003/06/10 11:51
		"4466864" "4856456" "5000827" "5169408"		
		"5312487" "5340437" "5472592" "5670034"		
		"5677000" "5893966" "5930549").PN.		
-	0	6214193.URPN.	USPAT	2003/06/10 11:51
_	17	("3798056" "3950184" "4339319" "4373988"	USPAT	2003/06/10 11:51
		"4466864" "4856456" "5000827" "5169408"		
		"5312487" "5340437" "5472592" "5670034"		
		"5677000" "5893966" "5930549" "6077412"		
		"6099702").PN.		·
_	33	6099702.URPN. (("3798056" "3950184"	USPAT;	2003/06/10 11:51
		"4339319" "4373988" "4466864" "4856456"	US-PGPUB;	2000,00,1011.51
		"5000827" "5169408" "5312487" "5340437"	EPO; JPO;	
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		"5930549").PN.) 6214193.URPN. (("3798056"	DERWEIT	
		"3950184" "4339319" "4373988" "4466864"		
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		"5893966" "5930549" "6077412"		
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		"6099702").PN.)	NEDWÉNE	2002/0//10
-	1	2001-580725.NRAN.	DERWENT	2003/06/10
	1.0	(/ /420702)	LICDAT	11:52
-	12	(("6139703") or ("6080291") or ("5932077") or	USPAT;	2003/06/10
		("5447615") or ("5421987") or ("5344491")).PN.	US-PGPUB;	12:29
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	836844.apn.	USPAT;	2003/06/10
			US-PGPUB;	12:47
			EPO; JPO;	
			DERWENT;	
]		IBW_TDB	
-	2401	204/199,212,232,263,275.1,297.01,297.06,297.07,297	.085RAT;	2003/06/10
			U5-PGPUB;	12:48
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

-	780	204/224r.ccls.	USPAT;	2003/06/10
			US-PGPUB;	12:48
			EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	3033	204/199,212,232,263,275.1,297.01,297.06,297.07,297	.08SaRAsT;	2003/06/10
		204/224r.ccls.	US-PGPUB;	12:48
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	73	(204/199,212,232,263,275.1,297.01,297.06,297.07,29		2003/06/10
		204/224r.ccls.) and ((multiple or plural\$3 or second)	US-PGPUB;	12:49
		near (outlet or withdraw\$3 or collect\$4))	EPO; JPO;	
		, ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DERWENT;	
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_	26	(204/199,212,232,263,275.1,297.01,297.06,297.07,29	_	2003/06/10
		204/224r.ccls.) and ((multiple or plural\$3) near	US-PGPUB;	12:49
		(outlet or withdraw\$3 or collect\$4))	EPO; JPO;	16.77
		(darier of wirning awas of collect \$47))	DERWENT;	
	4-7	//204/400 242 222 272 4 207 04 207 07 07 07 07	IBM_TDB	2002/07/40
-	47	((204/199,212,232,263,275.1,297.01,297.06,297.07,29		2003/06/10
		204/224r.ccls.) and ((multiple or plural\$3 or second)	U5-PGPUB;	12:52
		near (outlet or withdraw\$3 or collect\$4))) not	EPO; JPO;	
		((204/199,212,232,263,275.1,297.01,297.06,297.07,29		
		204/224r.ccls.) and ((multiple or plural\$3) near	IBW_TDB	
		(outlet or withdraw\$3 or collect\$4)))		
-	16	(204/199,212,232,263,275.1,297.01,297.06,297.07,29		2003/06/10
1		204/224r.ccls.) and (situ near (rins\$3 or process\$3	US-PGPUB;	12:56
		or clean\$3 or wash\$3))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	5932077.pn.	USPAT;	2004/01/07
			US-PGPUB;	14:58
-			EPO; JPO;	
:			DERWENT;	
1			IBM_TDB	
_	25	5932077.URPN.	USPAT	2004/01/07
				14:58
-	64	204/198,199.ccls. and (microelectronic or wafer or	USPAT;	2004/01/07
		semiconductor)	US-PGPUB;	15:12
		*	EPO; JPO;	
}			DERWENT;	
			IBM_TDB	
-	18	204/198,199.ccls. and (microelectronic or wafer or	USPAT;	2004/01/07
		semiconductor) and (spray\$4)	US-PGPUB;	15:12
		The second of th	EPO; JPO;	55.22
			DERWENT;	
			IBM_TDB	
_	2342	204/212,225,237,275.1.ccls.	USPAT;	2004/01/08
	2372	ao 1/ aia,aao,ao/ ,a/ 3.1.003.	US-PGPUB;	09:18
			EPO; JPO;	07.10
L			DERWENT	

-	811	204/224r.ccls.	USPAT;	2004/01/08
			US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT	
_	2957	204/212,225,237,275.1.ccls. 204/224r.ccls.	USPAT;	2004/01/08
			US-PGPUB;	09:18
			EPO; JPO;	
		^	DERWENT	
-	373	(204/212,225,237,275.1.ccls. 204/224r.ccls.) and	USPAT;	2004/01/08
		(wafer or semiconductor or microelectronic)	US-PGPUB;	09:19
		,	EPO; JPO;	
			DERWENT	
_	8	((204/212,225,237,275.1.ccls. 204/224r.ccls.) and	USPAT;	2004/01/08
		(wafer or semiconductor or microelectronic)) and	U5-PGPUB;	09:19
		(tilt\$5 and spray\$5)	EPO; JPO;	
		(, 5 24. 27. 27.	DERWENT	
_	14	((204/212,225,237,275.1.ccls. 204/224r.ccls.) and	USPAT;	2004/01/08
		(wafer or semiconductor or microelectronic)) and	U5-PGPUB;	10:12
		(tilt\$5 and (spray\$5 or nozzle))	EPO; JPO;	
		(Mingo and (Spray 40 St MS2210))	DERWENT	
	100	(204/198-227.ccls. and (microelectronic or wafer or	USPAT;	2004/01/08
	100	semiconductor)) and ((contact or electrode or	US-PGPUB;	11:48
		cathode) with (clean\$3 or wash\$3 or rins\$5))	EPO; JPO;	
		carriode) with (clean poor wash poor this poj)	DERWENT	
	2	6156167.pn.	USPAT;	2004/01/08
_		0150107.pn.	US-PGPUB;	11:48
			EPO; JPO;	11.40
			DERWENT	
	1	834844 ann	USPAT;	2004/01/09
-	1	836844.apn.	US-PGPUB;	09:24
			EPO; JPO;	03.24
		,	DERWENT;	
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	130	204/108 227 /wisses +	USPAT;	2004/01/09
_	438	204/198-227.ccls. and (microelectronic or wafer or	1	
		semiconductor)	US-PGPUB;	09:53
			EPO; JPO; DERWENT	
	30	(204/108 227 and and (minute) and a superior of the superior	1	2004/01/09
] -	20	(204/198-227.ccls. and (microelectronic or wafer or	USPAT;	
		semiconductor)) and (tilt\$4 with (wafer or substrate	US-PGPUB;	09:53
		or semiconductor or microelectronic))	EPO; JPO; DERWENT	
	5	6413214 nn 6259220 nn	USPAT;	2004/01/09
-	9	6613214.pn. 6258220.pn.		· ·
	:		US-PGPUB;	09:44
			EPO; JPO; DERWENT	
	-	4251224 mm 4258220 mm		2004/01/00
-	3	6251236.pn. 6258220.pn.	USPAT;	2004/01/09
			US-PGPUB;	09:44
			EPO; JPO;	
	44400	(005/4) 004/4	DERWENT	2004/04/00
-	11422	(205/\$.ccls. or 204/\$.ccls.) and (microelectronic or	USPAT;	2004/01/09
		wafer or semiconductor)	US-PGPUB;	09:53
			EPO; JPO;	
			DERWENT	

-	121	((205/\$.ccls. or 204/\$.ccls.) and (microelectronic or	USPAT;	2004/01/09
		wafer or semiconductor)) and (tilt\$4 with (wafer or	US-PGPUB;	09:54
		substrate or semiconductor or microelectronic))	EPO; JPO;	.0
			DERWENT	
	101	(((205/\$.ccls. or 204/\$.ccls.) and (microelectronic or	USPAT;	2004/01/09
		wafer or semiconductor)) and (tilt\$4 with (wafer or	US-PGPUB;	09:54
		substrate or semiconductor or microelectronic))) not	EPO; JPO;	
		((204/198-227.ccls. and (microelectronic or wafer or	DERWENT	
		semiconductor)) and (tilt\$4 with (wafer or substrate		
		or semiconductor or microelectronic)))		